EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L23	0	438/5.ccls. and ((model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (distributed adj simulat$4)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/07 15:17
L22	0	438/5.ccls. and ((model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (((re adj use) lookup) with result solution)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/07 15:17
L21	0	438/5.ccls. and ((model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (grid cell geometr$4 (physical adj geometr $4))).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/07 15:17
L20	29	(US-20040078319-$ or US-20050016947-$ or US-20030078738-$ or US-20040102934-$ or US-20030101251-$ or US-20050010319-$ or US-20020107604-$).did. or (US-6774998-$ or US-6757645-$ or US-6643616-$ or US-6763277-$ or US-6571371-$ or US-6728591-$ or US-6812045-$ or US-6628809-$ or US-6905895-$ or US-7333871-$ or US-6810296-$ or US-	US-PGPUB; USPAT	OR	ON	2011/05/07 15:12

		5583780-$ or US-6304834-$ or US-7055112-$ or US-6587744-$ or US-7184850-$ or US-7356377-$ or US-6560503-$ or US-5526293-$ or US-7622308-$).did. or (US-5866437-$ or US-20040078319-$ or WO-200277589-$ or US-20050010319-$ or WO-200177979-$ or US-20030135302-$ or JP-2007172210-$).did.				
L18	922	703/7.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/07 15:09
L17	26	438/5.ccls. and ((model$4 simulat$4) with (grid mesh element))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/07 14:57
L16	0	438/5.ccls. and ((model$4 simulat$4) with (grid mesh element) with (geometr$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/07 14:57
L15	281	438/5.ccls. and (model $4 simulat$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/07 14:56
L14	796	438/5.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/07 14:56

S160	0	703/7,13.ccls. and ((model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (distributed adj simulat$4)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 11:45
S159	0	700/121.ccls. and ((model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with ((plural$4 many multipl) adj simulat $4)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 11:44
S158	0	700/121.ccls. and ((model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (distributed adj simulat$4)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 11:44
S157	0	700/121.ccls. and ((model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (((re adj use) lookup) with result solution)). clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 11:43
S156	0	703/13.ccls. and ((model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (((re adj use) lookup) with result solution)). clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 11:43
S155	0	703/7.ccls. and ((model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (((re adj use) lookup) with result solution)). clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 11:43

S154	0	703/7.ccls. and ((model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (grid cell geometr$4 (physical adj geometr $4))).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 11:42
S153	71	((ANDREJ) near2 (MITROVIC)).INV.	US-PGPUB; USPAT; USOCR	OR	ON	2011/05/06 10:07
S152	106	((ERIC) near2 (STRANG)).INV.	US-PGPUB; USPAT; USOCR	OR	ON	2011/05/06 10:06
S151	2	703/13.ccls. and ((model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (grid cell geometr$4 (physical adj geometr $4))).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 10:06
S150	7	700/121.ccls. and ((model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (grid cell geometr$4 (physical adj geometr $4))).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 10:06
S149	83	S138 and S148	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:32
S148	2807	700/121.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:32
S147	234	700/121.ccls. and ((model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:32

S146	41	700/29-31.ccls. and ((model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:31
S145	0	700/29-31.ccls. and ((model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (grid))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:30
S144	0	"438"/$.ccls. and (model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment) with (distributed adj simulat$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:27
S143	0	"438"/$.ccls. and (model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment) with (code adj parallel$8))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:27
S142	13	"438"/$.ccls. and (model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment) with (grid geometr$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:26
S140	316	"438"/$.ccls. and (model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:25
S139	13	S137 and S138	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:17

S138	2441	700/29-31.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:17
S137	886	700/95.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:17
S136	5	((model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (grid))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:10
S135	1	703/13.ccls. and ((model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (grid))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:09
S134	0	703/7.ccls. and ((model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (grid))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:09
S133	0	703/13.ccls. and ((model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (grid)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:09
S131	0	703/7.ccls. and ((model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (grid)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:08

S129	2019	703/13.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/06 00:07
S128	2	"6802045".did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/05 23:58
S127	1404	703/22.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/05 23:55
S126	55	(semiconductor near3 (process$4 tool$4 equipment manufactur $4)) and ((model$ simulat$4) near5 ((physical geometry) near2 (machine tool manufactur$4 assembly))) and ((parallel near3 process$4) (code adj parallel$8) ((plural distributed multiple) near4 simulat$4) and grid)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/05 23:49
S125	6	(semiconductor near3 (process$4 tool$4 equipment manufactur $4)) and ((model$ simulat$4) near5 ((physical geometry) near2 (machine tool manufactur$4 assembly))) and ((re adj (using use)) with (known start$4 precomputed stor$4) with (result solution output))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/05 23:42

S124	61	(semiconductor near3 (process$4 tool$4 equipment manufactur $4)) and ((model$ simulat$4) near5 ((physical geometry) near2 (machine tool manufactur$4 assembly))) and ((parallel near3 process$4) (code adj parallel$8) ((plural distributed multiple) near4 simulat$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/05 23:40
S123	314	(semiconductor near3 (process$4 tool$4 equipment manufactur $4)) and ((model$ simulat$4) near5 ((physical geometry) near2 (machine tool manufactur$4 assembly)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/05 23:38
S122	12	(semiconductor near3 (process$4 tool$4 equipment manufactur $4)) with ((model$ simulat$4) near5 ((physical geometry) near2 (machine tool manufactur$4 assembly)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/05 23:35
S121	2	"6615097".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/05 23:31
S120	4	US-20020032495-$. DID. OR US-5719796-$.DID.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/05 23:28

EAST Search History (Interference)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp

L26	0	438/5.ccls. and ((model $4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (distributed adj simulat $4)).clm.	USPAT; UPAD	OR	ON	2011/05/07 15:18
L25	0	438/5.ccls. and ((model $4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (((re adj use) lookup) with result solution)).clm.	USPAT; UPAD	OR	ON	2011/05/07 15:18
L24	0	438/5.ccls. and ((model $4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (grid cell geometr$4 (physical adj geometr$4))).clm.	USPAT; UPAD	OR	ON	2011/05/07 15:18
S163	0	703/7.ccls. and ((model $4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (grid cell geometr$4 (physical adj geometr$4))).clm.	USPAT; UPAD	OR	ON	2011/05/06 11:42
S162	1	703/13.ccls. and ((model $4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (grid cell geometr$4 (physical adj geometr$4))).clm.	USPAT; UPAD	OR	ON	2011/05/06 11:39
S161	1	700/121.ccls. and ((model$4 simulat$4) with (semiconductor near2 (tool assembly manufactur$4 equipment)) with (grid cell geometr$4 (physical adj geometr$4))).clm.	USPAT; UPAD	OR	ON	2011/05/06 11:39

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